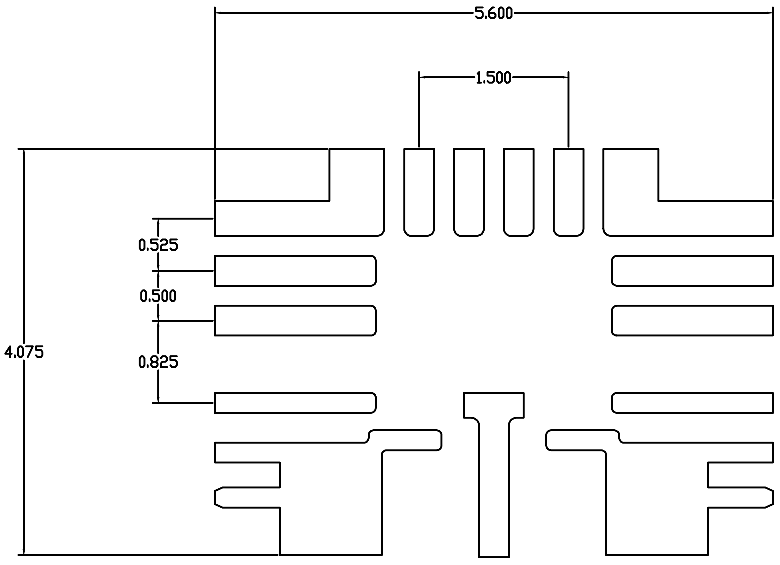
CHANGE DETAILS

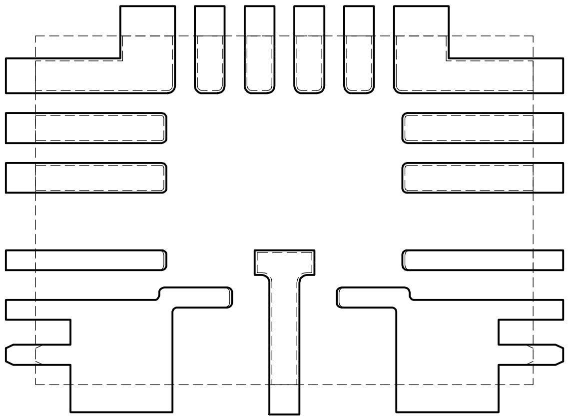
FROM	TO
	INITIAL RELEASE

Maxim Integrated	**TITLE:** PACKAGE LAND PATTERN, [F173A5FY+2] FC2QFN		
	DOCUMENT I.D. 90-100198	**REVISION** A	**PAGE** 1

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100557
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.
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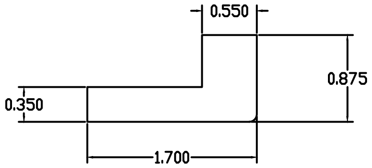
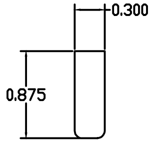
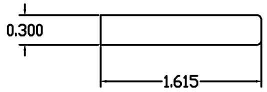
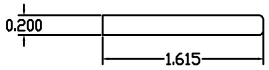
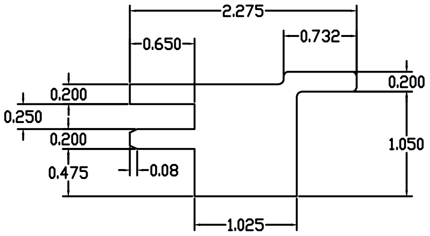
PAD DETAILS

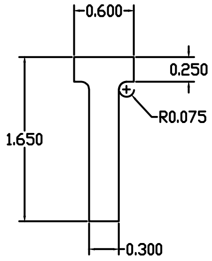












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